

Fabrication and characteristics of the nc-Si/c-Si heterojunction MAGFET*

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Abstract: A MAGFET using an nc-Si/c-Si heterojunction as source and drain was fabricated by CMOS technology, using two ohm-contact electrodes as Hall outputs on double sides of the channel situated $0.7L$ from the source. The experimental results show that when $V_{DS} = -7.0$ V, the magnetic sensitivity of the single nc-Si/c-Si heterojunction magnetic metal oxide semiconductor field effect transistor (MAGFET) with an $L : W$ ratio of $2 : 1$ is 21.26 mV/T, and that with an $L : W$ ratio of $4 : 1$ is 13.88 mV/T. When the outputs of double nc-Si/c-Si heterojunction MAGFETs with an $L : W$ ratio of $4 : 1$ are in series, their magnetic sensitivity is 22.74 mV/T, which is an improvement of about 64% compared with that of a single nc-Si/c-Si heterojunction MAGFET.

Key words: nc-Si/c-Si heterojunction; MAGFET; CMOS technology; serial output; magnetic sensitivity

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1. Introduction

The Hall effect was discovered by Dr. Edwin Hall in 1879 at Johns Hopkins University. The MOS device was first proposed as a magnetic sensor by Gallagher and Corak in 1966. A MAGFET (magnetic metal oxide semiconductor field effect transistor) consists of a MOSFET structure with additional contacts in the channel region.

In recent years, with the development of CMOS technology, a large number of MAGFET studies have been carried out at home and abroad^[1,2]. By studying the influence of channel size and channel shape (rectangular, concave, convex type, sector, etc.) on the magnetic properties of the MAGFET^[3-9], the magnetic sensitivity of the MAGFET could be improved.

In this paper, a MAGFET is fabricated on n-type $\langle 100 \rangle$ crystal silicon with high resistance ($\rho > 100 \Omega \cdot \text{cm}$) by CMOS technology, using an nc-Si/c-Si heterojunction as source and drain, with a Hall output as the series output to improve its magnetic sensitivity.

2. Basic structure and operation principle

2.1. Basic structure

The basic structure of the nc-Si/c-Si heterojunction MAGFET is shown in Fig. 1: (a) top view, (b) cross-section A-A' of the nc-Si/c-Si heterojunction MAGFET. The nc-Si/c-Si heterojunction MAGFET has a source, drain, gate, substrate and the two ohm-contact electrodes, which are taken as Hall outputs on double sides of the channel situated $0.7L$ from the source. The nc-Si/c-Si heterojunction MAGFET source and substrate are connected together, so $V_{BS} = 0$ V.

2.2. Operation principle

Equations (1) and (2) respectively give the I - V charac-

teristic equations of the p-MOSFET lying in the linear and saturation fields^[10]:

$$I_{DS} = -\frac{\mu_p C_{ox} W}{2} \frac{W}{L} \left[2(|V_{GS}| - |V_{TP}|) |V_{DS}| - |V_{DS}|^2 \right], \quad (1)$$

$$I_{DS} = -\frac{\mu_p C_{ox} W}{2} \frac{W}{L} (|V_{GS}| - |V_{TP}|)^2, \quad (2)$$

where μ_p is the carrier mobility, C_{ox} is the gate oxide capacitance per unit area, W and L are channel width and length, V_{TP} is the threshold voltage, V_{GS} is the gate to source voltage, and V_{DS} is the drain to source voltage.

The operation principle of the single nc-Si/c-Si heterojunction MAGFET is shown in Fig. 2. When there is no magnetic field ($B = 0$), drain current distribution is uniform, as shown in Fig. 2(a).

Theoretically, the Hall outputs on both sides of the channel should be the same potential; the Hall output voltage is:

$$V_H = V_{H1} - V_{H2} = 0. \quad (3)$$

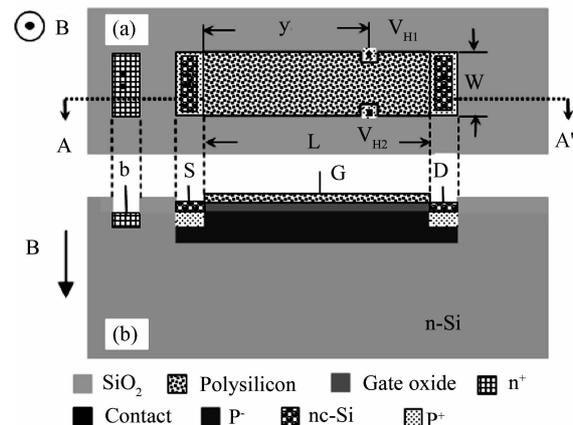


Fig. 1. Basic structure of the nc-Si/c-Si heterojunction MAGFET: (a) Top view; (b) Cross-section A-A'.

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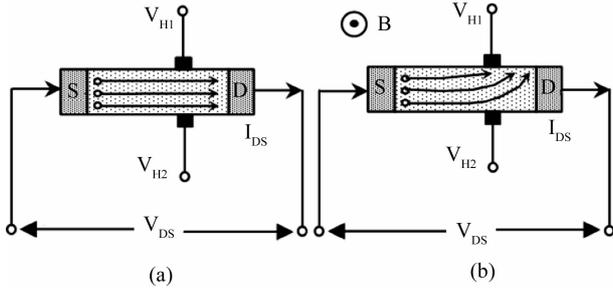


Fig. 2. Operation principle of the nc-Si/c-Si heterojunction MAGFET: (a) $B = 0$ T; (b) $B \neq 0$ T.

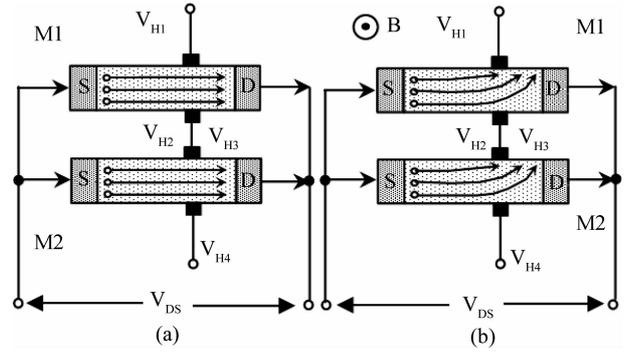


Fig. 3. Series output of the double nc-Si/c-Si heterojunction MAGFETs: (a) $B = 0$ T; (b) $B \neq 0$ T.

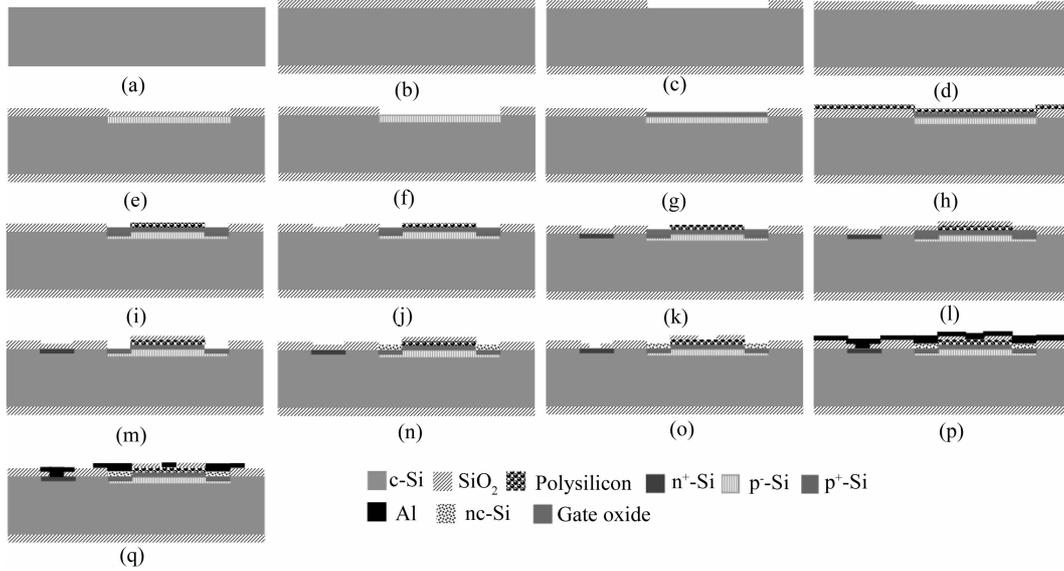


Fig. 4. Fabrication process of the nc-Si/c-Si heterojunction MAGFET.

When an additional magnetic field B is applied orthogonally to the MAGFET gate surface, the Lorentz force will force the channel carriers to deflect, which will change the current I_{DS} . The Hall voltage V_H of the single nc-Si/c-Si heterojunction MAGFET generated by a magnetic field B perpendicular to the MAGFET surface is given by

$$V_H = \mu_p \frac{W}{L} \frac{|V_{DS}|}{2 \left[1 - \frac{x}{L} \right]^{1/2}} B \cdot f'_H \left(\frac{L}{W}, \theta \right), \quad (4)$$

where x is the Hall output electrode position, and $f'_H \left(\frac{L}{W}, \theta \right)$ is the geometrical correction factor.

Series output structure diagrams of the double nc-Si/c-Si heterojunction MAGFETs are shown in Fig. 3. When there is no magnetic field ($B = 0$), the Hall voltages of M1 and M2 are as follows:

$$V_H = V_{M1} - V_{M2} = (V_{H1} - V_{H2}) - (V_{H3} - V_{H4}) = 0. \quad (5)$$

When a magnetic field B is applied to the nc-Si/c-Si heterojunction MAGFET, the Hall voltages of M1 and M2 are as follows:

$$V_H = V_{M1} - V_{M2} = 2\mu_p \frac{W}{L} \frac{|V_{DS}|}{2 \left[1 - \frac{x}{L} \right]^{1/2}} B f'_H \left(\frac{L}{W}, \theta \right). \quad (6)$$

Using Eqs. (4) and (6), under the same working condi-

tions, the series Hall output voltage of the double nc-Si/c-Si heterojunction MAGFETs is theoretically twice that of the single nc-Si/c-Si heterojunction MAGFET.

3. Fabrication

Figure 4 shows the fabrication technology process of the nc-Si/c-Si heterojunction MAGFET chip: (a) n-type $\langle 100 \rangle$ double sided polished single crystal silicon wafer with high resistance and thickness $450 \mu\text{m}$; (b) first oxidation: thermal oxidation process to grow silicon oxide (SiO_2) with thickness of 650 nm ; (c) first lithography to form the active region window of the nc-Si/c-Si heterojunction MAGFET; (d) second oxidation: thermal oxidation process to grow silicon oxide (SiO_2) with thickness of 50 nm in order to improve ion implantation uniformity; (e) using an ion implantation machine to obtain p-type implantation by injecting B ions: the energy of the implanted ions is 40 keV , and the dose of the implanted ions is $6.0 \times 10^{13} \text{ cm}^{-2}$; (f) etching silicon oxide (SiO_2) with thickness of 50 nm ; (g) third oxidation to grow gate oxide with thickness of 50 nm ; (h) depositing polysilicon by LPCVD and polysilicon P diffusion; (i) second lithography, etching polysilicon to form a polysilicon gate and B ion implantation, so that the MOSFET source and drain with p-type doping are formed; (j) third lithography to form substrate contact hole opening; (k)

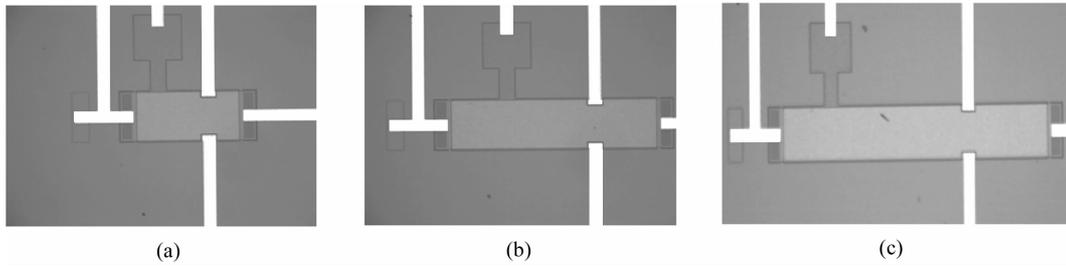


Fig. 5. Basic structure photographs of the nc-Si/c-Si heterojunction MAGFET with different channel length-width ratios: (a) $L : W = 2 : 1$; (b) $L : W = 4 : 1$; (c) $L : W = 6 : 1$.

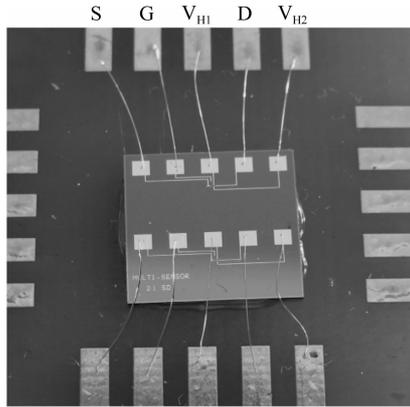


Fig. 6. Package structure photograph of the nc-Si/c-Si heterojunction MAGFET chip.

implanting P to form n^+ substrate; (l) polysilicon oxide to grow silicon oxide with thickness of 59.7 nm; (m) fourth lithography to source and drain of the p-MOSFET; (n) depositing nc-Si thin films with thickness of 30 nm by LPCVD and fifth lithography; (o) sixth lithography to etch contact hole opening; (p) depositing aluminum electrode by magnetron sputtering on the positive silicon wafer; (q) seventh lithography to form aluminum electrodes, source, drain, gate, substrate and Hall output electrode contacts of the nc-Si/c-Si heterojunction MAGFET.

Figures 5(a), 5(b) and 5(c) respectively show structure photographs of the nc-Si/c-Si heterojunction MAGFET chips with different channel length-width ratios of 2 : 1, 4 : 1 and 6 : 1. Figure 6 is a package test structure photograph of the nc-Si/c-Si heterojunction MAGFET chip, which shows the source (S), drain (D), gate (G), substrate (B) and Hall output V_{H1} , V_{H2} of the sensor.

4. Experimental results and discussion

4.1. Magnetic characteristics

At room temperature, the magnetic characteristics of the nc-Si/c-Si heterojunction MAGFET were tested by an HP34401A multimeter and a magnetic field generator; the additional magnetic field range was from -0.5 T to 0.5 T, the supply voltage V_{DS} is 0 to -7.0 V, $V_{BS} = 0$ V, and the gate is vacant.

When the supply voltage V_{DS} is given different values, Figures 7(a), 7(b), 7(c) show the respective magnetic characteristic curves for Hall output voltage V_H and the additional magnetic field B of the single nc-Si/c-Si heterojunction

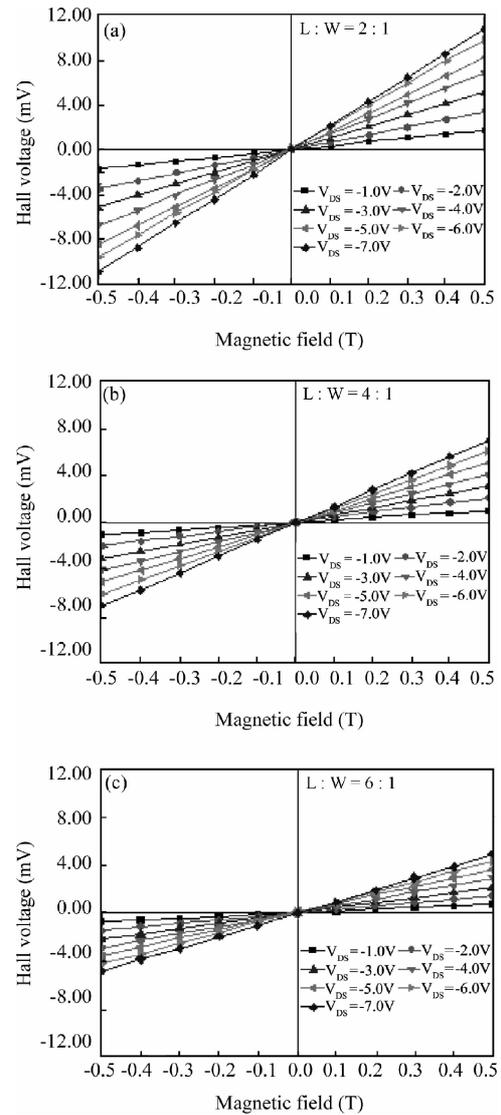


Fig. 7. Magnetic characteristics curves of the MAGFET at room temperature: (a) $L : W = 2 : 1$; (b) $L : W = 4 : 1$; (c) $L : W = 6 : 1$.

MAGFET with $L : W$ ratios of 2 : 1, 4 : 1 and 6 : 1. When the additional magnetic field B is constant, with an increasing absolute value of supply voltage V_{DS} , the output voltage V_H of the nc-Si/c-Si heterojunction MAGFET gradually increases. When the supply voltage $V_{DS} = -7.0$ V, the magnetic sensitivity of the single nc-Si/c-Si heterojunction MAGFET with an $L : W$ ratio of 2 : 1 is 21.26 mV/T, and the accuracy is 1.834% FS; the magnetic sensitivity of the single nc-Si/c-Si heterojunction MAGFET with an $L : W$ ratio of 4 : 1 is 13.88 mV/T, and that with an $L : W$ ratio of 6 : 1 is 9.76 mV/T.

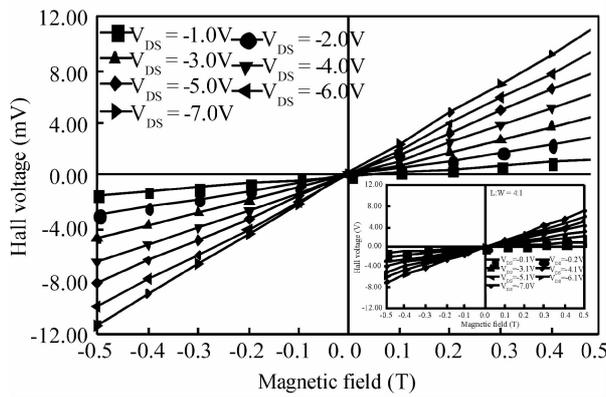


Fig. 8. Magnetic characteristics curves of series output of the double nc-Si/c-Si heterojunction MAGFETs with length-width ratio of 4 : 1.

Figure 8 shows the magnetic characteristic curves of the series outputs of the double nc-Si/c-Si heterojunction MAGFETs with an $L : W$ ratio of 4 : 1; the iconograph shows the magnetic characteristics curves of the single nc-Si/c-Si heterojunction MAGFET. By using the nc-Si/c-Si heterojunction as a series output, when $V_{DS} = -7.0$ V, the magnetic sensitivity of the double nc-Si/c-Si heterojunction MAGFETs with an $L : W$ ratio of 4 : 1 is 22.74 mV/T, which is an improvement of about 64% compared with that of the single nc-Si/c-Si heterojunction MAGFET.

4.2. Temperature characteristics

A Shanghai Blue Leopard LGS-010C high and low temperature chamber was used to do high and low temperature experiments on the nc-Si/c-Si heterojunction MAGFET with a ratio of 4 : 1 from -20 to 60 °C when the supply voltage V_{DS} was -1.0 V; the experimental curves of temperature characteristics for the single nc-Si/c-Si heterojunction MAGFET are shown in Fig. 9.

By using a certain magnetic field B and the supply voltage V_{DS} , the Hall voltage temperature coefficient is given in Eq. (7):

$$\alpha = \frac{1}{V_H} \frac{\partial V_H}{\partial T} = \frac{V_H(T_2) - V_H(T_1)}{V_H(T_1) \times (T_2 - T_1)} \times 100\% \approx -0.439\%/^{\circ}\text{C}, \quad (7)$$

where $V_H(T_1)$ is the Hall voltage of the temperature T_1 , and $V_H(T_2)$ is the Hall voltage of the temperature T_2 .

5. Conclusion

A MAGFET using an nc-Si/c-Si heterojunction as source and drain was fabricated by CMOS technology; its magnetic sensitivity is proportional to the absolute value of the supply voltage V_{DS} . When $V_{DS} = -7.0$ V, the magnetic sensitivities of the single nc-Si/c-Si heterojunction MAGFET with length-width ratios of 2 : 1, 4 : 1, 6 : 1 are 21.26 mV/T, 13.88 mV/T and 9.76 mV/T, respectively. By using the series Hall output

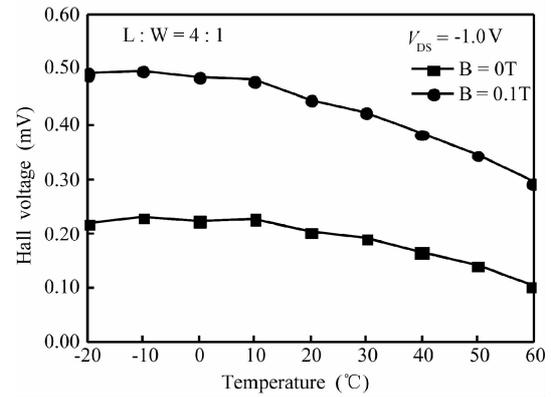


Fig. 9. Temperature characteristics curves of the nc-Si/c-Si heterojunction MAGFET with length-width ratio of 4 : 1.

of the double nc-Si/c-Si heterojunction MAGFETs with an $L : W$ ratio of 4 : 1, the magnetic sensitivity of the MAGFET is 22.74 mV/T, which is an improvement of about 64% compared with that of the single MAGFET, 13.88 mV/T. The experimental results show that by using the double nc-Si/c-Si heterojunction MAGFETs series output, the magnetic sensitivity of the nc-Si/c-Si heterojunction MAGFET could be clearly improved.

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